

0.8A, 50V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- · Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- · Freewheeling application

MECHANICAL DATA

- Case: Sub SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.019g (approximately)

| KEY PARAMETERS | | | | |
|--------------------|------------|------|--|--|
| PARAMETER | VALUE | UNIT | | |
| I _F | 0.8 | Α | | |
| V_{RRM} | 50 - 1000 | V | | |
| I _{FSM} | 30 | Α | | |
| T _{J MAX} | 150 | °C | | |
| Package | Sub SMA | | | |
| Configuration | Single die | | | |









Sub SMA



| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | | | | | |
|--|------------------|-------------------------------|------------|------------|------------|------------|------------|------------|------|
| PARAMETER | SYMBOL | RS1 ALH | RS1 BLH | RS1 DLH | RS1 GLH | RS1 JLH | RS1 KLH | RS1 MLH | UNIT |
| Marking code on the device | | RAL | RBL | RDL | RGL | RJL | RKL | RML | |
| Repetitive peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Reverse voltage, total rms value | $V_{R(RMS)}$ | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Forward current | I _F | 0.8 | | | | Α | | | |
| Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load | I _{FSM} | I _{FSM} 30 | | | | А | | | |
| Junction temperature | TJ | T _J - 55 to +150 | | | °C | | | | |
| Storage temperature | T _{STG} | T _{STG} - 55 to +150 | | | °C | | | | |



| THERMAL PERFORMANCE | | | | |
|--|------------------|-----|------|--|
| PARAMETER | SYMBOL | ТҮР | UNIT | |
| Junction-to-lead thermal resistance | R _{OJL} | 32 | °C/W | |
| Junction-to-ambient thermal resistance | $R_{\Theta JA}$ | 105 | °C/W | |

| ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted) | | | | | | |
|--|------------------|---------------------------------|-----------------|-----|-----|------|
| PARAMETER | | CONDITIONS | SYMBOL | TYP | MAX | UNIT |
| Forward voltage ⁽¹⁾ | | $I_F = 0.8A, T_J = 25^{\circ}C$ | V _F | - | 1.3 | V |
| Reverse current @ rated V _R ⁽²⁾ | | T _J = 25°C | I _R | - | 5 | μA |
| | | T _J = 125°C | | - | 50 | μA |
| Junction capacitance | | 1MHz, $V_R = 4.0V$ | CJ | 10 | - | pF |
| RS1A RS1E RS1D Reverse recovery time | | IF = 0.5A, IR = 1.0A, | t _{rr} | - | 150 | ns |
| reverse recovery time | RS1JLH | I _{rr} = 0.25A | rr . | - | 250 | ns |
| | RS1KLH RS1MLH | | | - | 500 | ns |

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

| ORDERING INFORMATION | | | | |
|------------------------------|---------|----------------------|--|--|
| ORDERING CODE ⁽¹⁾ | PACKAGE | PACKING | | |
| RS1xLH | Sub SMA | 10,000 / Tape & Reel | | |

Notes:

1. "x" defines voltage from 50V(RS1ALH) to 1000V(RS1MLH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

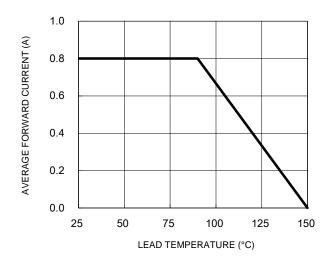


Fig.3 Typical Reverse Characteristics

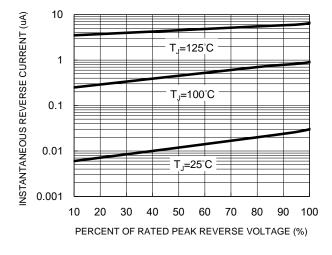


Fig.2 Typical Junction Capacitance

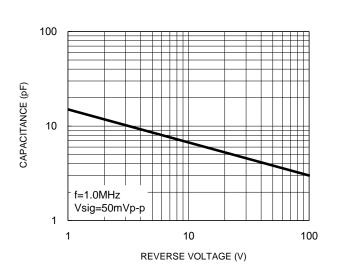


Fig.4 Typical Forward Characteristics

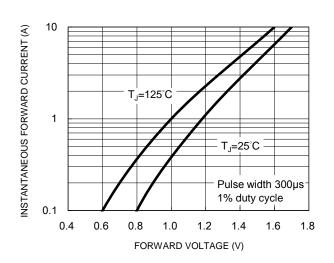
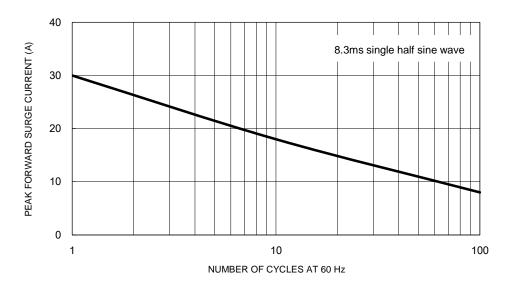


Fig.5 Maximum Non-Repetitive Forward Surge Current



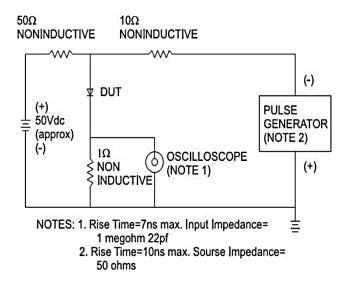


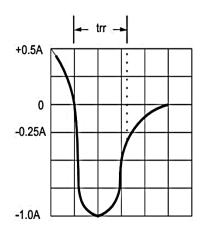
Taiwan Semiconductor

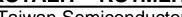
CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram



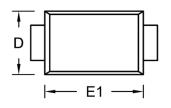


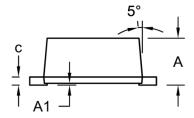


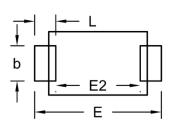


PACKAGE OUTLINE DIMENSIONS

Sub SMA

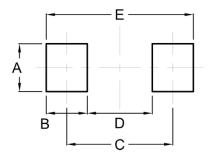






| DIM. | Unit (mm) | | Unit (| (inch) | |
|--------|-----------|------|--------|--------|--|
| Dilvi. | Min. | Max. | Min. | Max. | |
| А | 1.23 | 1.43 | 0.048 | 0.056 | |
| A1 | 0.00 | 0.10 | 0.000 | 0.004 | |
| b | 0.80 | 1.20 | 0.031 | 0.047 | |
| С | 0.16 | 0.30 | 0.006 | 0.012 | |
| D | 1.70 | 1.90 | 0.067 | 0.075 | |
| E | 3.40 | 3.80 | 0.134 | 0.150 | |
| E1 | 2.70 | 2.90 | 0.106 | 0.114 | |
| E2 | 2.45 | 2.60 | 0.096 | 0.102 | |
| L | 0.35 | 0.85 | 0.014 | 0.033 | |

SUGGESTED PAD LAYOUT



| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| Α | 1.40 | 0.055 |
| В | 1.20 | 0.047 |
| С | 3.10 | 0.122 |
| D | 1.90 | 0.075 |
| E | 4.30 | 0.169 |

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.